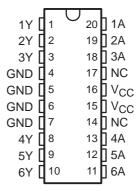
- Flow-Through Architecture Optimizes
  PCB Layout
- Center-Pin V<sub>CC</sub> and GND Configuration Minimizes High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, and Standard Plastic 300-mil DIPs (N)

## DB, DW, OR N PACKAGE (TOP VIEW)

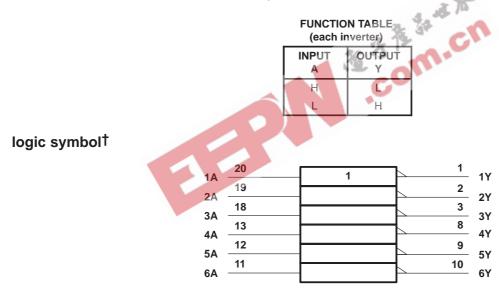


NC - No internal connection

#### description

This device contains six independent inverters. It performs the Boolean function  $Y = \overline{A}$ .

The 74AC11004 is characterized for operation from -40°C to 85°C.



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

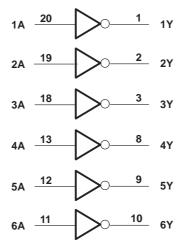


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#### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Output voltage range, VO (see Note 1)	
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see	ee Note 2): DW package 1.6 W
	DB package 0.6 W
	N package 1.3 W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The maximum package power dissipation is calculated using a junction temperature of 150 °C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.



### recommended operating conditions

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		3	5	5.5	V
		V <sub>CC</sub> = 3 V	2.1			
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			V
	V <sub>CC</sub> = 5.5 V	3.85				
		V <sub>CC</sub> = 3 V			0.9	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 4.5 V			1.35	V
	V <sub>CC</sub> = 5.5 V			1.65		
٧ <sub>I</sub>	Input voltage	-	0		Vcc	V
۷o	Output voltage		0		Vcc	V
		V <sub>CC</sub> = 3 V			-4	
loh	High-level output current	V <sub>CC</sub> = 4.5 V			-24	mA
		V <sub>CC</sub> = 5.5 V			-24	
		V <sub>CC</sub> = 3 V			12	
$I_{OL}$	Low-level output current	V <sub>CC</sub> = 4.5 V			24	mA
		V <sub>CC</sub> = 5.5 V			24	
Δt/Δν	Input transition rise or fall rate	3. St.	0		10	ns/V
TA	Operating free-air temperature	3.12	-40		85	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	T <sub>A</sub> = 25°C		MIN	MAV	UNIT	
PARAMETER	TEST CONDITIONS	vcc -	MIN	TYP	MAX	l WIIIN	MAX	UNIT
	I <sub>OH</sub> = -50 μA	3 V	2.9			2.9		
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
VOH	IOH = -4  mA	3 V	2.58			2.48		V
		4.5 V	3.94			3.8		
	I <sub>OH</sub> = -24 mA	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	I <sub>OL</sub> = 50 μA	3 V			0.1		0.1	
		4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
VOL	I <sub>OL</sub> = 12 mA	3 V			0.36		0.44	V
	1- 04 mA	4.5 V			0.36		0.44	
	I <sub>OL</sub> = 24 mA				0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		3.5				pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



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#### switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T <sub>A</sub> = 25°C		MIN MAX	MAV	UNIT		
	PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIN	IVIAA	UNIT
	<sup>t</sup> PLH		V	1.5	6.1	9	1.5	10	no
	<sup>t</sup> PHL	A	ſ	1.5	5.2	7.4	1.5	8.2	ns

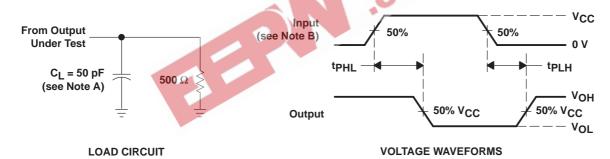
#### switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	TO T <sub>A</sub> = 25°C	MIN	MAX	UNIT		
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIN	WAX	UNIT
t <sub>PLH</sub>	۸	V	1.5	4.2	6.3	1.5	7.1	no
t <sub>PHL</sub>	A	ī	1.5	3.8	5.5	1.5	6	ns

### operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

	PARAMETER	TEST CO	NDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per inverter	C <sub>L</sub> = 50 pF,	f = 1 MHz	29	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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